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TI - LAMINATED GLASS-CERAMIC CIRCUIT BOARD  
PN - JP8236936 A 19960913  
AP - JP19950038819 19950227  
OPD - 1995-02-27  
PR - JP19950038819 19950227  
PA - KYOCERA CORP  
IN - FURUHASHI KAZUMASA  
IC - H05K3/46 ; B32B7/02 ; B32B17/06 ; B32B18/00 ; H05K1/03  
ICO - T05K1/00B2 ; T05K1/03B ; T05K3/46B

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TI - Laminate glass-ceramic circuit substrate which resists contraction - consists of internal wiring conductor formed of low resistance metallic materials arranged between insulation layer of glass component and inorganic filler

AB - J08236936 The substrate comprises a laminate base sheet (1) in which insulation layers (1a - 1e) consisting of a glass component and an inorganic filler are laminated and a via hole conductor (3) consisting of an internal wiring conductor (2) formed of low resistance metallic materials is arranged between the adjoining layers of the insulation layers and a low resistance metallic material arranged at the insulation layer. The laminate base sheet (1) is formed such that the insulation layers (1a - 1e) consist of glass components having respective glass transition points which are different by at least 80 deg.C.

- ADVANTAGE - The percentage of contraction in the direction of a plane of a laminate base sheet occurring during burning is suppressed to a low value.

- (Dwg.1/1)

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AN - 1996-470318 [47]

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TI - LAMINATED GLASS-CERAMIC CIRCUIT BOARD  
AB - PURPOSE: To reduce the degree of shrinkage of a laminated glass-ceramic

circuit board at the time of baking the board by forming the circuit board by laminating a plurality of insulating layers containing glass components having glass- transition temperatures which are different from each other by a specific value or more.

- CONSTITUTION: A laminated glass-ceramic circuit board is composed of a laminated board 1 containing circuits and surface wiring conductors 4 and 5, a thick resistor film, and a protective film are formed and electronic parts 6 connected to the conductors 4 and 5 are mounted on the main surface of the board 1 at need. The laminated board 1 is composed of insulating layers 1a-1e, internal wiring conductors 2, and via hole conductors 3 and the circuits are formed in the board 1. The glass-transition temperatures of the glass components contained in some of the insulating layers 1a-1e constituting the board 1, for example, in the insulating layers 1a and 1e are different from those of the glass components contained in the other insulating layers 1b-1d by 80 deg.C.

Therefore, the degree of shrinkage of the laminated board 1 can be reduced at the time of baking the board 1, because the shrinkage stresses generated in the insulating layers 1a-1e can be dispersed.

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